CD54HC597, CD74HC597, CD74HCT597

Data sheet acquired from Harris Semiconductor
SCHS191C

January 1998 - Revised October 2003

High-Speed CMOS Logic 8-Bit Shift Register with Input Storage

Features

- **Buffered Inputs**
- **Asynchronous Parallel Load**
- **Fanout (Over Temperature Range)**
  - **Standard Outputs . . . . . 10 LSTTL Loads**
  - **Bus Driver Outputs . . . . . 15 LSTTL Loads**
- **Wide Operating Temperature Range . . . -55^{O}C to 125^{O}C**
- **Balanced Propagation Delay and Transition Times**
- **Significant Power Reduction Compared to LSTTL Logic ICs**
- **HC Types**
  - **2V to 6V Operation**
  - **High Noise Immunity: N_{IL} = 30%, N_{IH} = 30% of V_{CC} at V_{CC} = 5V**
- **HCT Types**
  - **4.5V to 5.5V Operation**
  - **Direct LSTTL Input Logic Compatibility, V_{IL}= 0.8V (Max), V_{IH} = 2V (Min)**
  - **CMOS Input Compatibility, $I_I \leq 1\mu A$ at V_{OL}, V_{OH}**

Description

The ’HC597 and CD74HCT597 are high-speed silicon gate CMOS devices that are pin-compatible with the LSTTL 597 devices. Each device consists of an 8-flip-flop input register and an 8-bit parallel-in/serial-in, serial-out shift register. Each register is controlled by its own clock. A “low” on the parallel load input ($\overline{PL}$) shifts parallel stored data asynchronously into the shift register. A “low” master input ($\overline{MR}$) clears the shift register. Serial input data can also be synchronously shifted through the shift register when $\overline{PL}$ is high.

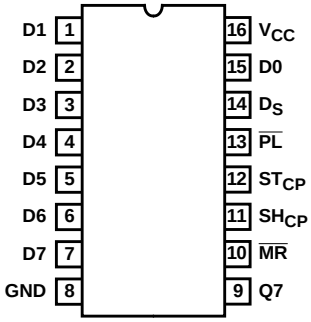
Ordering Information

PART NUMBER	TEMP. RANGE (^{O}C)	PACKAGE
CD54HC597F3A	-55 to 125	16 Ld CERDIP
CD74HC597E	-55 to 125	16 Ld PDIP
CD74HC597M	-55 to 125	16 Ld SOIC
CD74HC597MT	-55 to 125	16 Ld SOIC
CD74HC597M96	-55 to 125	16 Ld SOIC
CD74HC597NSR	-55 to 125	16 Ld SOP
CD74HCT597E	-55 to 125	16 Ld PDIP
CD74HCT597M	-55 to 125	16 Ld SOIC
CD74HCT597MT	-55 to 125	16 Ld SOIC
CD74HCT597M96	-55 to 125	16 Ld SOIC

NOTE: When ordering, use the entire part number. The suffixes 96 and R denote tape and reel. The suffix T denotes a small-quantity reel of 250.

Pinout

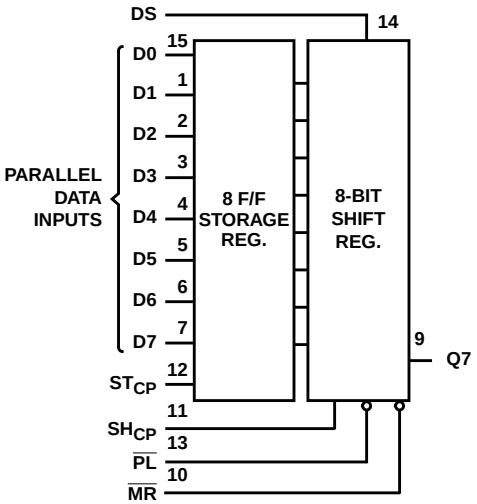
CD54HC597
(CERDIP)
CD74HC597
(PDIP, SOIC, SOP)
CD74HCT597
(PDIP, SOIC)
TOP VIEW



CAUTION: These devices are sensitive to electrostatic discharge. Users should follow proper IC Handling Procedures.

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Functional Diagram



FUNCTION TABLE

ST_{CP}	SH_{CP}	$\overline{PL}$	$\overline{MR}$	FUNCTION
↑	X	X	X	Data Loaded to Input Flip-Flops
↑	X	L	H	Data Loaded from Inputs to Shift Register
No Clock Edge	X	L	H	Data Transferred from Input Flip-Flops to Shift Register
X	X	L	L	Invalid Logic, State of Shift Register Indeterminate when Signals Removed
X	X	H	L	Shift Register Cleared
X	↑	H	H	Shift Register Clocked Qn = Qn-1, Q0 = D_S

H = High Voltage Level, L = Low Voltage Level, X = Don't Care, ↑ = Transition from Low to High CP Level

Absolute Maximum Ratings

DC Supply Voltage, V_{CC} . . . . . -0.5V to 7V
DC Input Diode Current, I_{IK}
For V_I < -0.5V or V_I > V_{CC} + 0.5V . . . . . ±20mA
DC Output Diode Current, I_{OK}
For V_O < -0.5V or V_O > V_{CC} + 0.5V . . . . . ±20mA
DC Drain Current, per Output, I_O
For -0.5V < V_O < V_{CC} + 0.5V . . . . . ±25mA
DC Output Source or Sink Current per Output Pin, I_O
For V_O > -0.5V or V_O < V_{CC} + 0.5V . . . . . ±25mA
DC V_{CC} or Ground Current, I_{CC} . . . . . ±50mA

Operating Conditions

Temperature Range, T_A . . . . . -55°C to 125°C
Supply Voltage Range, V_{CC}
HC Types . . . . . 2V to 6V
DC Input or Output Voltage, V_I, V_O . . . . . 0V to V_{CC}
Input Rise and Fall Time
2V . . . . . 1000ns (Max)
4.5V. . . . . 500ns (Max)
6V . . . . . 400ns (Max)

Thermal Information

Thermal Resistance (Typical, Note 1) θ_{JA} (°C/W)
E (PDIP) Package 67
M (SOIC) Package. 73
NS (SOP) Package 64
Maximum Junction Temperature . . . . . 150°C
Maximum Storage Temperature Range . . . . . -65°C to 150°C
Maximum Lead Temperature (Soldering 10s) . . . . . 300°C
(SOIC - Lead Tips Only)

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

1. The package thermal impedance is calculated in accordance with JESD 51-7.

DC Electrical Specifications

PARAMETER	SYMBOL	TEST CONDITIONS		V_{CC} (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
		V_I (V)	I_O (mA)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
HC TYPES												
High Level Input Voltage	V_{IH}	-	-	2	1.5	-	-	1.5	-	1.5	-	V
				4.5	3.15	-	-	3.15	-	3.15	-	V
				6	4.2	-	-	4.2	-	4.2	-	V
Low Level Input Voltage	V_{IL}	-	-	2	-	-	0.5	-	0.5	-	0.5	V
				4.5	-	-	1.35	-	1.35	-	1.35	V
				6	-	-	1.8	-	1.8	-	1.8	V
High Level Output Voltage CMOS Loads	V_{OH}	V_{IH} or V_{IL}	-0.02	2	1.9	-	-	1.9	-	1.9	-	V
			-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
			-0.02	6	5.9	-	-	5.9	-	5.9	-	V
High Level Output Voltage TTL Loads			-	-	-	-	-	-	-	-	-	V
			-4	4.5	3.98	-	-	3.84	-	3.7	-	V
			-5.2	6	5.48	-	-	5.34	-	5.2	-	V
Low Level Output Voltage CMOS Loads	V_{OL}	V_{IH} or V_{IL}	0.02	2	-	-	0.1	-	0.1	-	0.1	V
			0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
			0.02	6	-	-	0.1	-	0.1	-	0.1	V
Low Level Output Voltage TTL Loads			-	-	-	-	-	-	-	-	-	V
			4	4.5	-	-	0.26	-	0.33	-	0.4	V
			5.2	6	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	I_I	V_{CC} or GND	-	6	-	-	±0.1	-	±1	-	±1	µA

DC Electrical Specifications (Continued)

PARAMETER	SYMBOL	TEST CONDITIONS		V_{CC} (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
		V_I (V)	I_O (mA)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
Quiescent Device Current	I_{CC}	V_{CC} or GND	0	6	-	-	8	-	80	-	160	µA
HCT TYPES												
High Level Input Voltage	V_{IH}	-	-	4.5 to 5.5	2	-	-	2	-	2	-	V
Low Level Input Voltage	V_{IL}	-	-	4.5 to 5.5	-	-	0.8	-	0.8	-	0.8	V
High Level Output Voltage CMOS Loads	V_{OH}	V_{IH} or V_{IL}	-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
High Level Output Voltage TTL Loads			-4	4.5	3.98	-	-	3.84	-	3.7	-	V
Low Level Output Voltage CMOS Loads	V_{OL}	V_{IH} or V_{IL}	0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
Low Level Output Voltage TTL Loads			4	4.5	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	I_I	V_{CC} and GND	0	5.5	-		±0.1	-	±1	-	±1	µA
Quiescent Device Current	I_{CC}	V_{CC} or GND	0	5.5	-	-	8	-	80	-	160	µA
Additional Quiescent Device Current Per Input Pin: 1 Unit Load	ΔI_{CC} (Note 2)	V_{CC} -2.1	-	4.5 to 5.5	-	100	360	-	450	-	490	µA

NOTE:

2. For dual-supply systems theoretical worst case (V_I = 2.4V, V_{CC} = 5.5V) specification is 1.8mA.

HCT Input Loading Table

INPUT	UNIT LOADS
D_S	0.2
D_n	0.3
$\overline{PL}$, $\overline{MR}$	1.5
ST_{CP}, SH_{CP}	1.5

NOTE: Unit Load is ΔI_{CC} limit specified in DC Electrical Specifications Table, e.g., 360µA max. at 25°C.

Prerequisite for Switching Specifications

PARAMETER	SYMBOL	V_{CC} (V)	25°C			-40°C TO 85°C			-55°C TO 125°C			UNITS
			MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
HC TYPES												
SH_{CP} Frequency	f_{MAX}	2	6	-	-	5	-	-	4	-	-	MHz
		4.5	30	-	-	25	-	-	20	-	-	MHz
		6	35	-	-	29	-	-	23	-	-	MHz

Prerequisite for Switching Specifications (Continued)

PARAMETER	SYMBOL	V_{CC} (V)	25°C			-40°C TO 85°C			-55°C TO 125°C			UNITS
			MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
SH_{CP} Pulse Width	t_W	2	80	-	-	100	-	-	120	-	-	ns
		4.5	16	-	-	20	-	-	24	-	-	ns
		6	14	-	-	17	-	-	20	-	-	ns
ST_{CP} Pulse Width	t_W	2	60	-	-	75	-	-	90	-	-	ns
		4.5	12	-	-	15	-	-	18	-	-	ns
		6	10	-	-	13	-	-	15	-	-	ns
$\overline{MR}$ Pulse Width	t_W	2	80	-	-	100	-	-	120	-	-	ns
		4.5	16	-	-	20	-	-	24	-	-	ns
		6	14	-	-	17	-	-	20	-	-	ns
$\overline{PL}$ Pulse Width	t_W	2	70	-	-	90	-	-	105	-	-	ns
		4.5	14	-	-	18	-	-	21	-	-	ns
		6	12	-	-	15	-	-	18	-	-	ns
ST_{CP} to SH_{CP} Setup Time	t_{SU}	2	100	-	-	125	-	-	150	-	-	ns
		4.5	20	-	-	25	-	-	30	-	-	ns
		6	17	-	-	21	-	-	26	-	-	ns
D_S to SH_{CP} Setup Time D_n to ST_{CP} Setup Time	t_{SU}	2	50	-	-	65	-	-	75	-	-	ns
		4.5	10	-	-	13	-	-	15	-	-	ns
		6	9	-	-	11	-	-	13	-	-	ns
ST_{CP} to SH_{CP} Setup Time	t_H	2	0	-	-	0	-	-	0	-	-	ns
		4.5	0	-	-	0	-	-	0	-	-	ns
		6	0	-	-	0	-	-	0	-	-	ns
D_S to SH_{CP} Hold Time D_n to ST_{CP} Hold Time	t_H	2	3	-	-	3	-	-	3	-	-	ns
		4.5	3	-	-	3	-	-	3	-	-	ns
		6	3	-	-	3	-	-	3	-	-	ns
MR to SH_{CP} Removal Time	t_{REM}	2	3	-	-	3	-	-	3	-	-	ns
		4.5	3	-	-	3	-	-	3	-	-	ns
		6	3	-	-	3	-	-	3	-	-	ns
HCT TYPES												
SH_{CP} Frequency	f_{MAX}	4.5	25	-	-	20	-	-	16	-	-	MHz
SH_{CP} Pulse Width	t_W	4.5	20	-	-	25	-	-	30	-	-	ns
ST_{CP} Pulse Width	t_W	4.5	13	-	-	16	-	-	20	-	-	ns
$\overline{MR}$ Pulse Width	t_W	4.5	18	-	-	23	-	-	27	-	-	ns
$\overline{PL}$ Pulse Width	t_W	4.5	16	-	-	20	-	-	24	-	-	ns
ST_{CP} to SH_{CP} Setup Time	t_{SU}	4.5	24	-	-	30	-	-	36	-	-	ns

Prerequisite for Switching Specifications (Continued)

PARAMETER	SYMBOL	V_{CC} (V)	25°C			-40°C TO 85°C			-55°C TO 125°C			UNITS
			MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
D_S to SH_{CP} Setup Time D_n to ST_{CP} Setup Time	t_H	4.5	10	-	-	13	-	-	15	-	-	ns
ST_{CP} to SH_{CP} Hold Time	t_H	4.5	0	-	-	0	-	-	0	-	-	ns
D_S to SH_{CP} Hold Time D_n to ST_{CP} Hold Time	t_H	4.5	3	-	-	3	-	-	3	-	-	ns
MR to SH_{CP} Removal Time	t_{REM}	4.5	10	-	-	13	-	-	15	-	-	ns

Switching Specifications Input t_r, t_f = 6ns

PARAMETER	SYMBOL	TEST CONDITIONS	V_{CC} (V)	25°C			-40°C to 85°C		-55°C to 125°C		UNITS
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
HC TYPES											
Propagation Delay	t_{PLH}, t_{PHL}	C_L = 50pF	2	-	-	175	-	220	-	265	ns
SH_{CP} to Q7			4.5	-	-	35	-	44	-	53	ns
		C_L =15pF	5	-	14	-	-	-	-	-	ns
		C_L = 50pF	6	-	-	30	-	37	-	45	ns
$\overline{PL}$ to Q7	t_{PLH}, t_{PHL}	C_L = 50pF	2	-	-	200	-	250	-	300	ns
			4.5	-	-	40	-	50	-	60	ns
		C_L =15pF	5	-	17	-	-	-	-	-	ns
		C_L = 50pF	6	-	-	34	-	43	-	51	ns
ST_{CP} to Q7	t_{PLH}, t_{PHL}	C_L = 50pF	2	-	-	240	-	300	-	360	ns
			4.5	-	-	48	-	60	-	72	ns
		C_L =15pF	5	-	20	-	-	-	-	-	ns
		C_L = 50pF	6	-	-	41	-	51	-	61	ns
$\overline{MR}$ to Q7	t_{PLH}, t_{PHL}	C_L = 50pF	2	-	-	175	-	220	-	265	ns
			4.5	-	-	35	-	44	-	53	ns
		C_L =15pF	5	-	14	-	-	-	-	-	ns
		C_L = 50pF	6	-	-	30	-	37	-	45	ns
Output Transition Time	t_{TLH}, t_{THL}	C_L = 50pF	2	-	-	75	-	95	-	110	ns
			4.5	-	-	15	-	19	-	22	ns
			6	-	-	13	-	16	-	19	ns
Input Capacitance	C_I	C_L = 50pF	-	-	-	10	-	10	-	10	pF
Power Dissipation Capacitance, (Notes 3, 4)	C_{PD}	-	5	-	13.5	-	-	-	-	-	pF
HCT											
Propagation Delay SH_{CP} to Q7	t_{PLH}, t_{PHL}	C_L = 50pF	4.5	-	-	38	-	48	-	57	ns
		C_L = 15pF	5	-	16	-	-	-	-	-	ns
$\overline{PL}$ to Q7	t_{PLH}, t_{PHL}	C_L = 50pF	4.5	-	-	48		60		72	ns
		C_L = 15pF	5	-	20	-	-	-	-	-	ns
ST_{CP} to Q7	t_{PLH}, t_{PHL}	C_L = 50pF	4.5	-	-	56		70		84	ns
		C_L = 15pF	5	-	23	-	-	-	-	-	ns

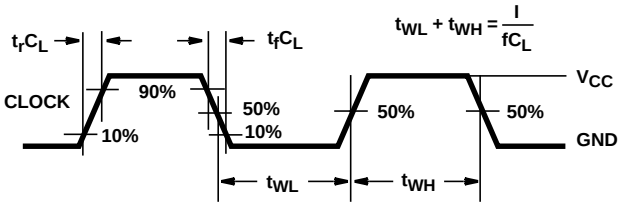
Switching Specifications Input t_r, t_f = 6ns **(Continued)**

PARAMETER	SYMBOL	TEST CONDITIONS	V_{CC} (V)	25°C			-40°C to 85°C		-55°C to 125°C		UNITS
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$\overline{MR}$ to Q7	t_{PLH}, t_{PHL}	C_L = 50pF	4.5	-	-	44	-	55	-	66	ns
		C_L = 15pF	5	-	18	-	-	-	-	-	ns
Output Transition Time	t_{TLH}, t_{THL}	C_L = 50pF	4.5	-	-	15	-	19	-	22	ns
Input Capacitance	C_I	C_L = 50pF	-	-	-	10	-	10	-	10	pF
Power Dissipation Capacitance, (Notes 3, 4)	C_{PD}	-	5	-	18.5	-	-	-	-	-	pF

NOTES:

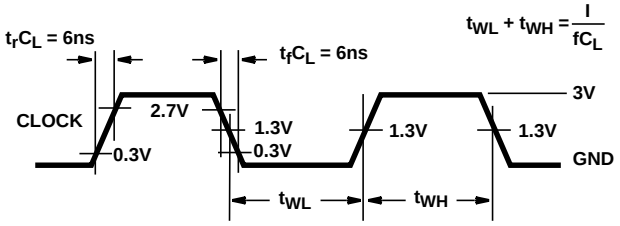
3. C_{PD} is used to determine the dynamic power consumption, per package.
4. $P_D = C_{PD} V_{CC}^2 f_i + \Sigma (C_L V_{CC}^2 f_o)$ where: f_i = Input Frequency, f_o = Output Frequency, C_L = Output Load Capacitance, V_{CC} = Supply Voltage.

Test Circuits and Waveforms



NOTE: Outputs should be switching from 10% V_{CC} to 90% V_{CC} in accordance with device truth table. For f_{MAX}, input duty cycle = 50%.

FIGURE 1. HC CLOCK PULSE RISE AND FALL TIMES AND PULSE WIDTH



NOTE: Outputs should be switching from 10% V_{CC} to 90% V_{CC} in accordance with device truth table. For f_{MAX}, input duty cycle = 50%.

FIGURE 2. HCT CLOCK PULSE RISE AND FALL TIMES AND PULSE WIDTH

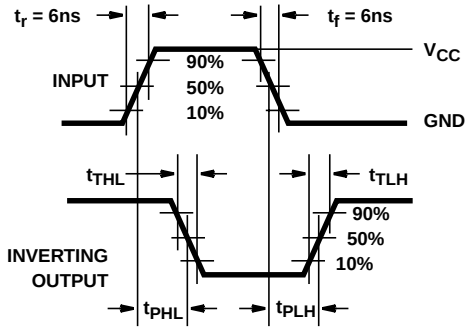


FIGURE 3. HC TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC

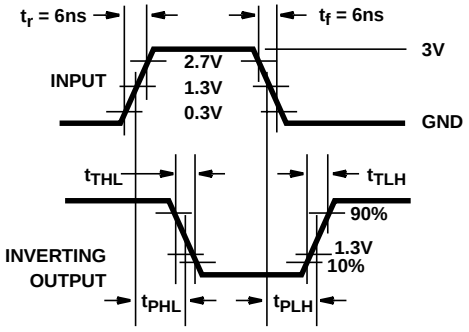


FIGURE 4. HCT TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC

Test Circuits and Waveforms (Continued)

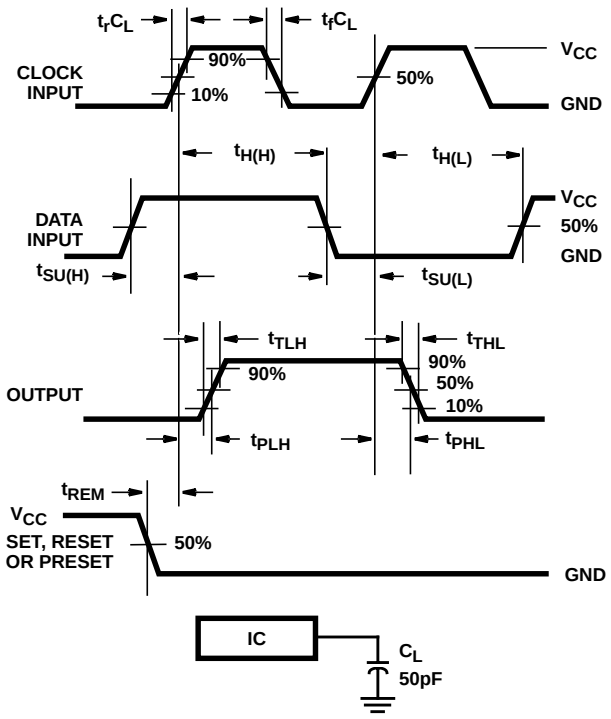


FIGURE 5. HC SETUP TIMES, HOLD TIMES, REMOVAL TIME, AND PROPAGATION DELAY TIMES FOR EDGE TRIGGERED SEQUENTIAL LOGIC CIRCUITS

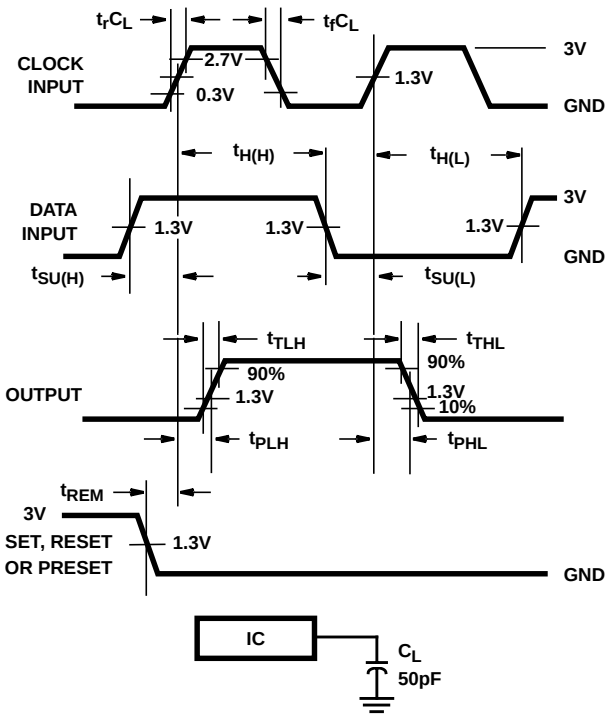
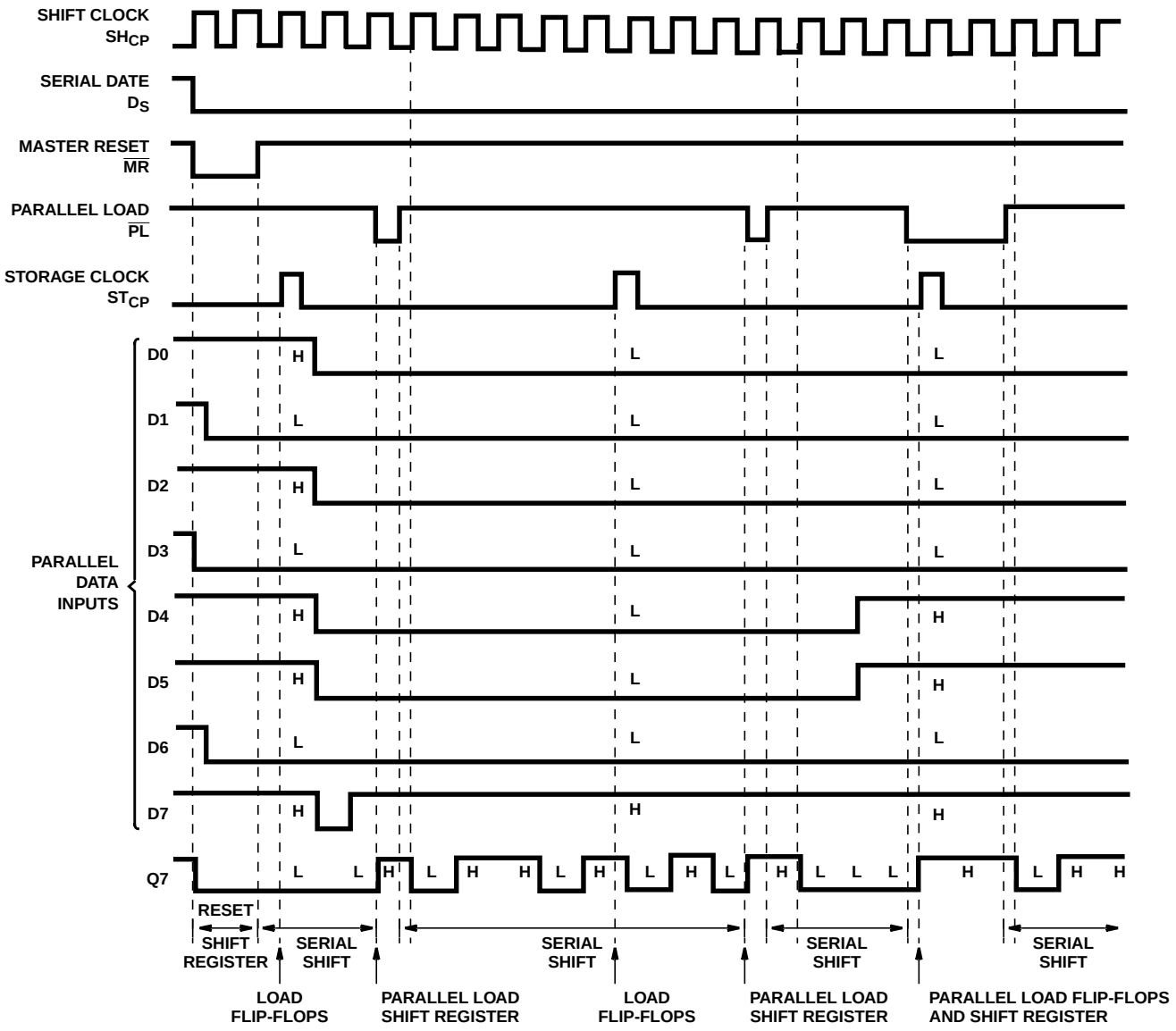


FIGURE 6. HCT SETUP TIMES, HOLD TIMES, REMOVAL TIME, AND PROPAGATION DELAY TIMES FOR EDGE TRIGGERED SEQUENTIAL LOGIC CIRCUITS

Timing Diagram



PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
5962-8681701EA	Active	Production	CDIP (J) | 16	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8681701EA CD54HC597F3A
CD54HC597F3A	Active	Production	CDIP (J) | 16	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8681701EA CD54HC597F3A
CD54HC597F3A.A	Active	Production	CDIP (J) | 16	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8681701EA CD54HC597F3A
CD74HC597E	Active	Production	PDIP (N) | 16	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74HC597E
CD74HC597E.A	Active	Production	PDIP (N) | 16	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74HC597E
CD74HC597EE4	Active	Production	PDIP (N) | 16	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74HC597E
CD74HC597M	Obsolete	Production	SOIC (D) | 16	-	-	Call TI	Call TI	-55 to 125	HC597M
CD74HC597M96	NRND	Production	SOIC (D) | 16	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC597M
CD74HC597M96.A	NRND	Production	SOIC (D) | 16	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC597M
CD74HC597M96E4	NRND	Production	SOIC (D) | 16	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC597M
CD74HC597M96G4	NRND	Production	SOIC (D) | 16	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC597M
CD74HC597MT	Obsolete	Production	SOIC (D) | 16	-	-	Call TI	Call TI	-55 to 125	HC597M
CD74HC597NSR	Active	Production	SOP (NS) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC597M
CD74HC597NSR.A	Active	Production	SOP (NS) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC597M
CD74HCT597E	Active	Production	PDIP (N) | 16	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74HCT597E
CD74HCT597E.A	Active	Production	PDIP (N) | 16	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74HCT597E
CD74HCT597M	Obsolete	Production	SOIC (D) | 16	-	-	Call TI	Call TI	-55 to 125	HCT597M
CD74HCT597M96	Last Time Buy	Production	SOIC (D) | 16	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT597M
CD74HCT597M96.A	Last Time Buy	Production	SOIC (D) | 16	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT597M
CD74HCT597MT	Obsolete	Production	SOIC (D) | 16	-	-	Call TI	Call TI	-55 to 125	HCT597M

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF CD54HC597, CD74HC597 :

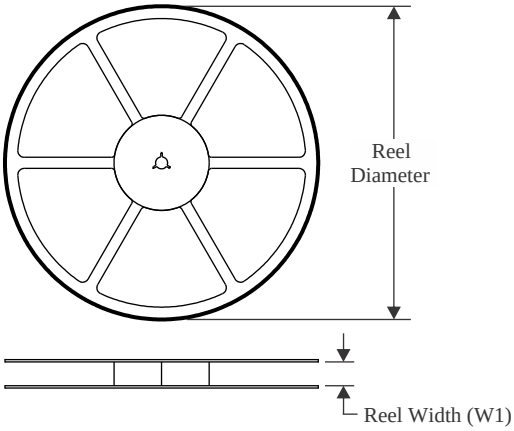
- Catalog : CD74HC597
- Military : CD54HC597

NOTE: Qualified Version Definitions:

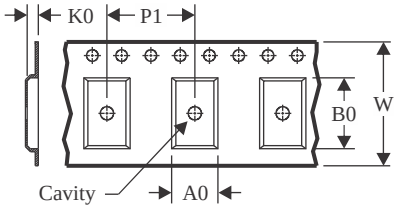
- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS

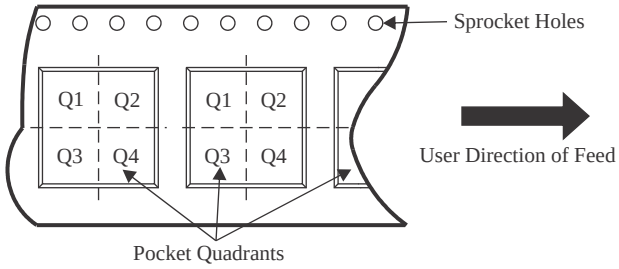


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

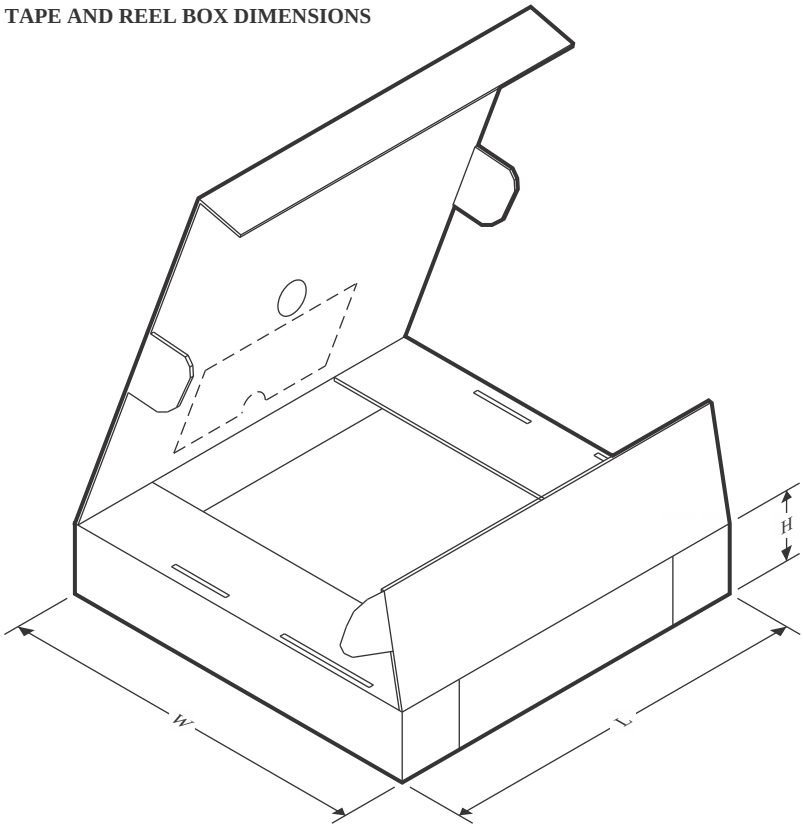
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74HC597M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74HC597NSR	SOP	NS	16	2000	330.0	16.4	8.1	10.4	2.5	12.0	16.0	Q1
CD74HCT597M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

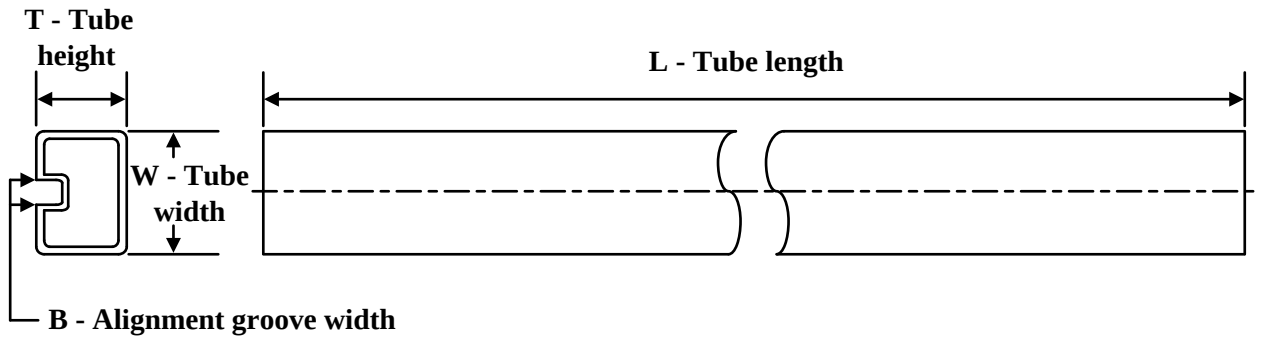
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

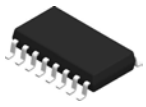
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74HC597M96	SOIC	D	16	2500	353.0	353.0	32.0
CD74HC597NSR	SOP	NS	16	2000	353.0	353.0	32.0
CD74HCT597M96	SOIC	D	16	2500	353.0	353.0	32.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
CD74HC597E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HC597E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HC597E.A	N	PDIP	16	25	506	13.97	11230	4.32
CD74HC597E.A	N	PDIP	16	25	506	13.97	11230	4.32
CD74HC597EE4	N	PDIP	16	25	506	13.97	11230	4.32
CD74HC597EE4	N	PDIP	16	25	506	13.97	11230	4.32
CD74HCT597E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HCT597E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HCT597E.A	N	PDIP	16	25	506	13.97	11230	4.32
CD74HCT597E.A	N	PDIP	16	25	506	13.97	11230	4.32

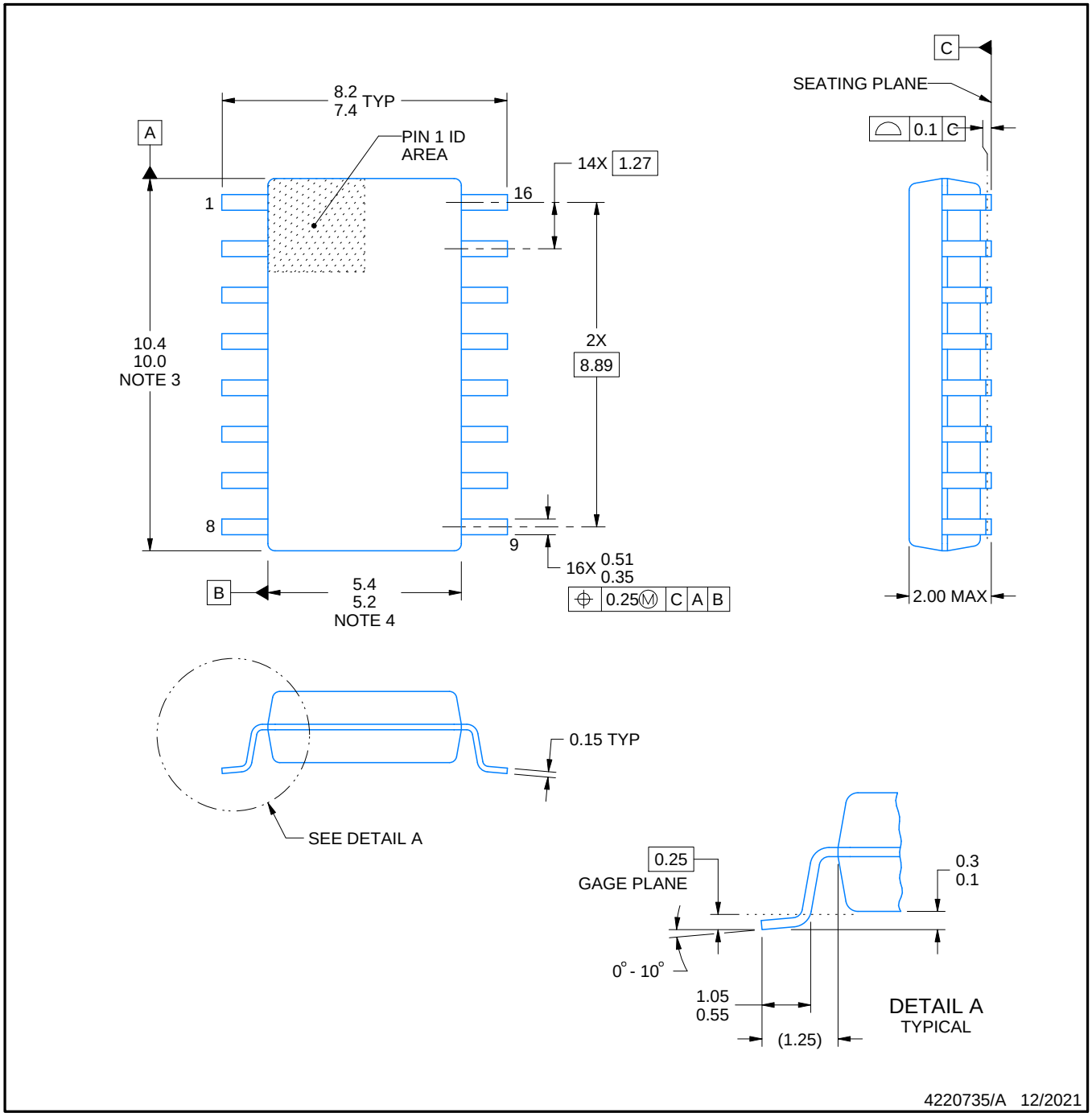


PACKAGE OUTLINE

NS0016A

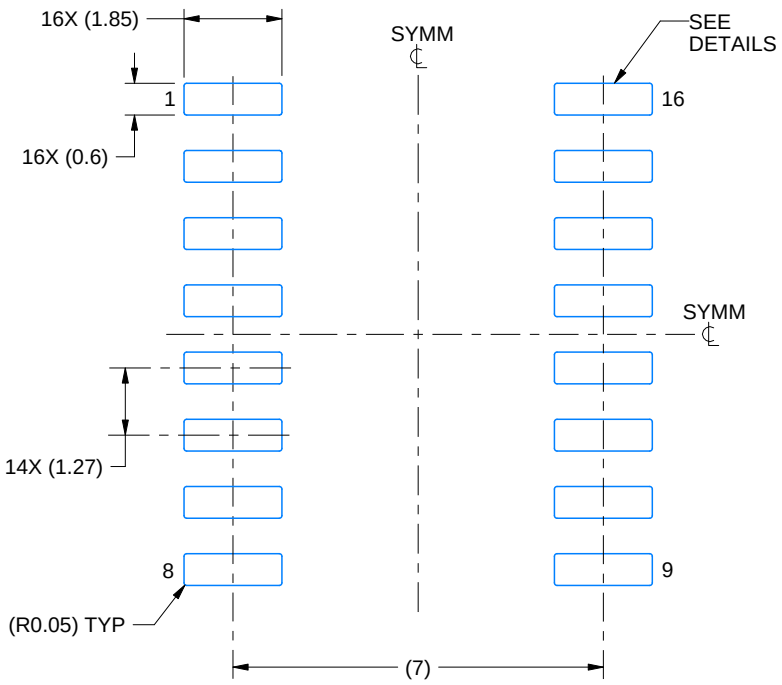
SOP - 2.00 mm max height

SOP

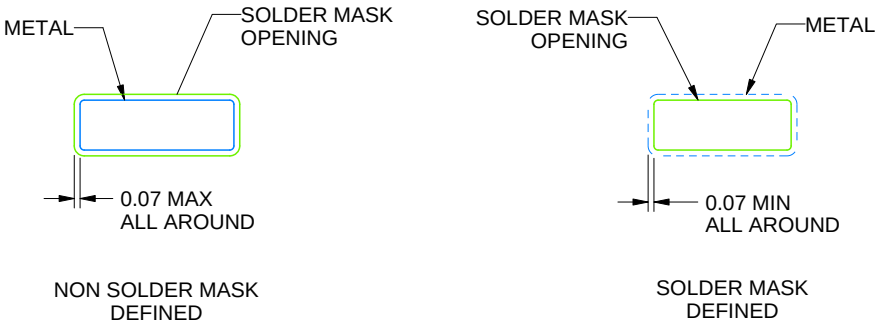


NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.



LAND PATTERN EXAMPLE
SCALE:7X



NON SOLDER MASK
DEFINED

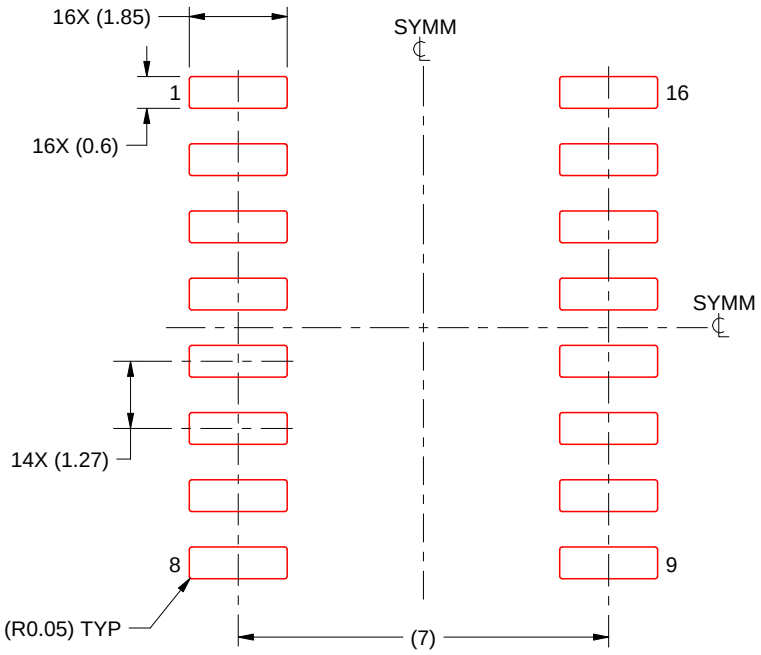
SOLDER MASK
DEFINED

SOLDER MASK DETAILS

4220735/A 12/2021

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



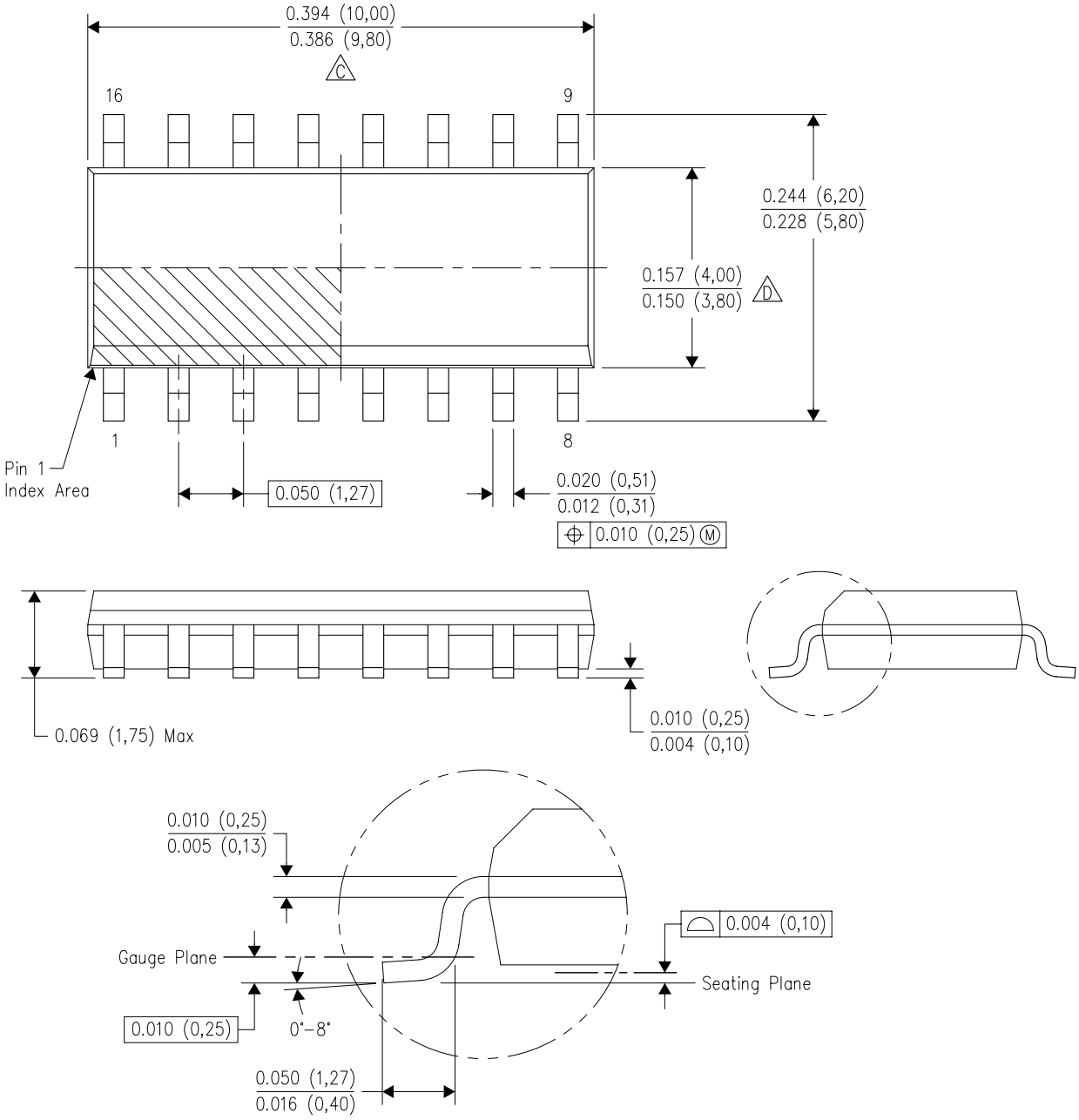
SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:7X

4220735/A 12/2021

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

D (R–PDSO–G16) PLASTIC SMALL OUTLINE

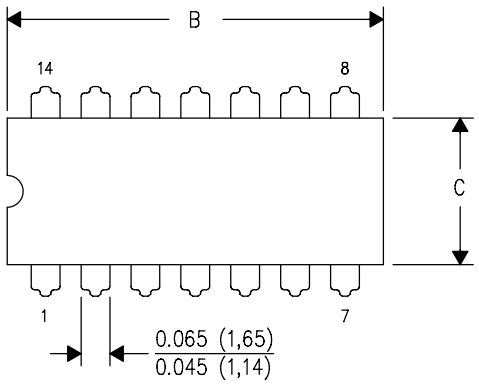


NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AC.

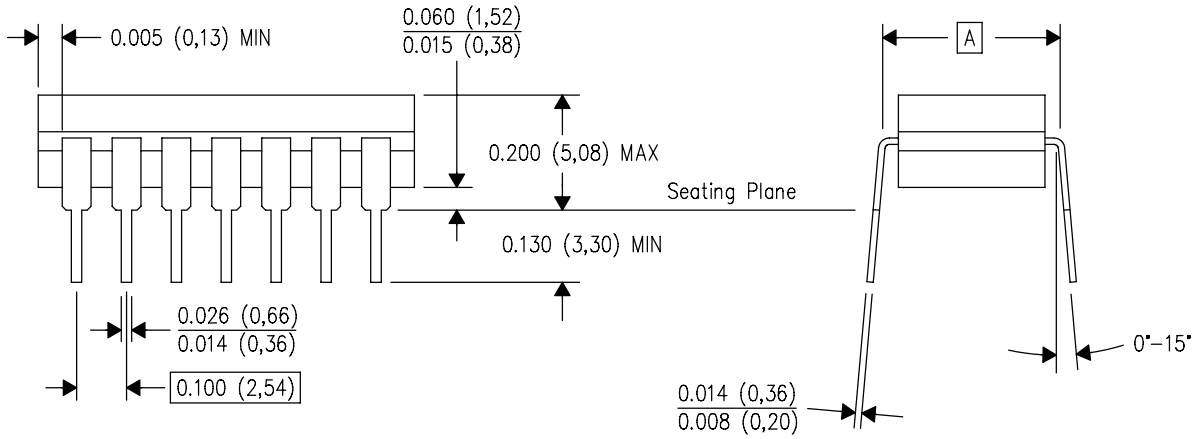
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



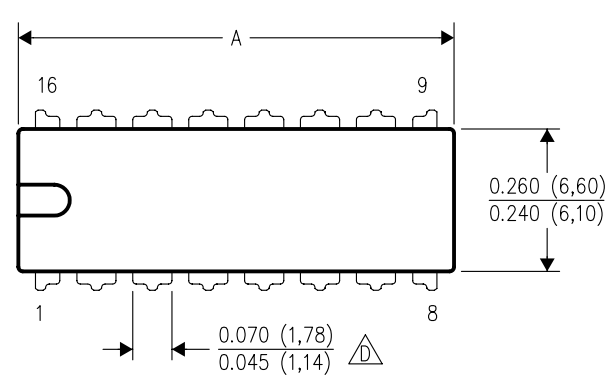
4040083/F 03/03

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

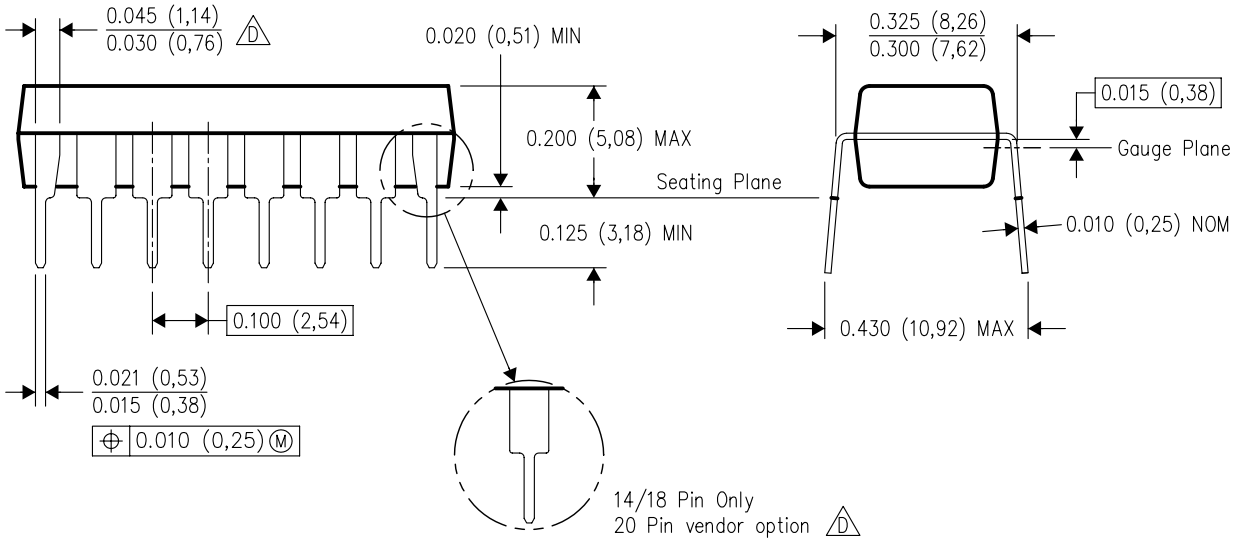
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

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